

SERIES 7000 CIRCUIT MEMO #19

**SUBJECT:**            METHODS OF PACKAGING MULTIPATH CORES  
FOR A HIGH-SPEED MEMORY

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**ABSTRACT:**        Three methods for packaging the SILO high-speed memory have been under consideration. The printed wiring scheme discussed in STM-9 is one such method. The other two methods utilize conventional wire. This memorandum discusses the experimental work conducted and the progress made with the printed wiring method, and describes the other two methods.

The work conducted in designing frames for use in the toroidal medium-speed memory array also is included in this memorandum

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